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## P-CHANNEL ENHANCEMENT MODE MOSFET

**DMG2307L** 

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
	90mΩ @ V <sub>GS</sub> = -10V	-3.8A
-30V	134mΩ @ V <sub>GS</sub> = -4.5V	-3.1A

#### **Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 standards for High Reliability

## **Description and Applications**

This MOSFET has been designed to minimize the on-state resistance  $(R_{DS(on)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

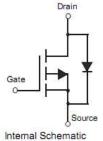
- General Purpose Interfacing Switch
- Power Management Functions
- Load Switch for Portable Devices

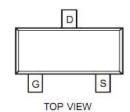
#### **Mechanical Data**

- Case: SOT-23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe.
   Solderable per MIL-STD-202, Method 208
- Weight: 0.08 grams (approximate)









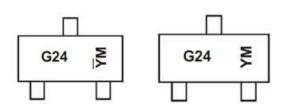
### Ordering Information (Notes 4 & 5)

Part Number	Compliance	Case	Packaging	
DMG2307L-7	Standard SOT-23		3000Tape & Reel	
DMG2307LQ-7	Automotive	SOT-23	3000Tape & Reel	

#### Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product\_compliance\_definitions/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



G24 = Product Type Marking Code

YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)

YM = Date Code Marking for CAT (Chengdu Assembly/ Test site) Y or Y = Year (ex: A = 2013)

M = Month (ex: 9 = September)

Chengdu A/T Site

Shanghai A/T Site

#### Date Code Key

Year	2009	2010	20	11	2012	2013	2014	2015	5 20	16	2017	2018
Code	W	Х	\	Y	Z	Α	В	С		0	Е	F
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		$V_{DSS}$	-30	V	
Gate-Source Voltage			$V_{GSS}$	±20	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = -10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-2.5 -2.0	А
Continuous Drain Current (Note 7) V <sub>GS</sub> = -10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-3.8 -3.0	А
Continuous Drain Current (Note 7) V <sub>GS</sub> = -10V	t ≦10sec	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-4.6 -3.6	А
Continuous Drain Current (Note 7) V <sub>GS</sub> = -4.5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-3.1 -2.5	А
Pulsed Drain Current (Note 7)			I <sub>DM</sub>	-20	Α

# Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 6)	$P_{D}$	0.76	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	159	°C/W
Total Power Dissipation (Note 7)	P <sub>D</sub>	1.36	W
Thermal Resistance, Junction to Ambient (Note 7)	$R_{\theta JA}$	94	°C/W
Total Power Dissipation (Note 7) $t \le 10$ sec	P <sub>D</sub>	1.9	W
Thermal Resistance, Junction to Ambient (Note 7) t ≤ 10sec	$R_{\theta JA}$	65.8	°C/W
Operating and Storage Temperature Range	$T_{J_{i}}T_{STG}$	-55 to +150	°C

## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)								
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	-30	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	@T <sub>C</sub> = +25°C	I <sub>DSS</sub>	_	_	-1.0	μΑ	$V_{DS} = -30V, V_{GS} = 0V$	
Gate-Source Leakage		I <sub>GSS</sub>	_	_	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	
ON CHARACTERISTICS (Note 8)								
Gate Threshold Voltage		$V_{GS(th)}$	-1.0	_	-3.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance			_	70	90	mΩ	$V_{GS} = -10V, I_D = -2.5A$	
Static Drain-Source On-Resistance		R <sub>DS (ON)</sub>	_	105	134	11177	$V_{GS} = -4.5V$ , $I_D = -2.5A$	
Forward Transfer Admittance		Y <sub>fs</sub>	ı	4.8	_	S	$V_{DS} = -10V, I_D = -2.5A$	
Diode Forward Voltage (Note 7)		V <sub>SD</sub>	_	-0.75	-1.0	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A	
DYNAMIC CHARACTERISTICS (Note 9)				•				
Input Capacitance	_	Ciss	ı	371.3	-	рF	15)( )(	
Output Capacitance		Coss	_	51.3	_	pF	$V_{DS} = -15V, V_{GS} = 0V,$ - f = 1.0MHz	
Reverse Transfer Capacitance		C <sub>rss</sub>	_	45.9	_	pF	1 - 1.0Wii iz	
Gate Resistance		Rg	_	17	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1.0MHz$	
Total Gate Charge (V <sub>GS</sub> = -4.5V)		Qg	_	4.0	_	nC		
Total Gate Charge (V <sub>GS</sub> = -10V)		Qg	_	8.2	_	nC	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -15V,	
Gate-Source Charge		Q <sub>gs</sub>	-	0.9	_	nC	I <sub>D</sub> = -3A	
Gate-Drain Charge		$Q_{qd}$	1	1.2	_	nC	7	
Turn-On Delay Time		t <sub>D(on)</sub>	-	4.8	_	ns		
Turn-On Rise Time		t <sub>r</sub>	-	7.3	_	ns	$V_{DS} = -15V, V_{GS} = -10V,$	
Turn-Off Delay Time		t <sub>D(off)</sub>	1	22.4	_	ns	$R_L = 15\Omega$ , $R_G = 6\Omega$ ,	
Turn-Off Fall Time		t <sub>f</sub>	-	13.4	_	ns	s I <sub>D</sub> = -1A	

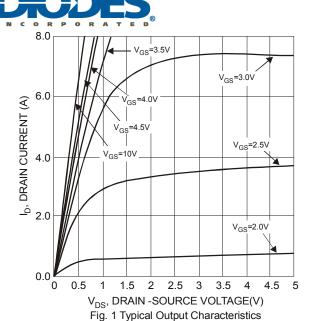
Notes: 6. Device mounted on FR-4 PCB, with minimum recommended pad layout.

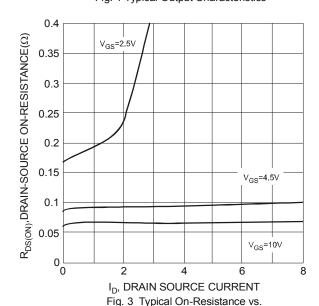
<sup>7.</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.

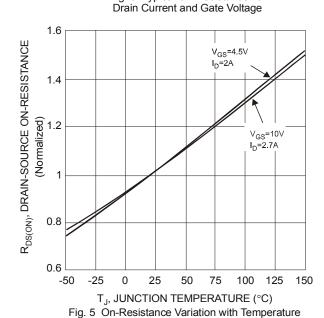
 $<sup>{\</sup>bf 8.\ Short\ duration\ pulse\ test\ used\ to\ minimize\ self-heating\ effect.}$ 

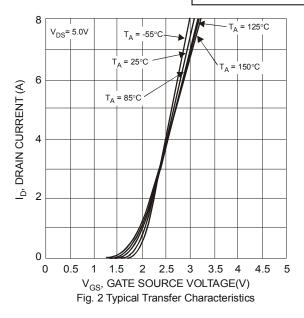
<sup>9.</sup> Guaranteed by design. Not subject to product testing.

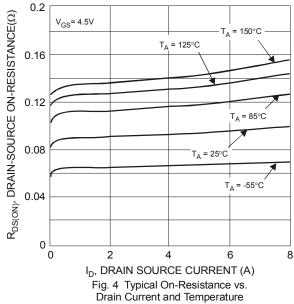












0.2  $R_{DS(ON)}$ , DRAIN-SOURCE ON-RESISTANCE  $(\Omega)$ 0.16 V<sub>GS</sub>=4.5V  $I_D = 2A$ 0.12 0.08 V<sub>GS</sub>=10V I<sub>D</sub>=2.7A 0.04 25 150 -50 -25 0 50 75 100 125 T<sub>.I</sub>, JUNCTION TEMPERATURE (°C)

Fig. 6 On-Resistance Variation with Temperature



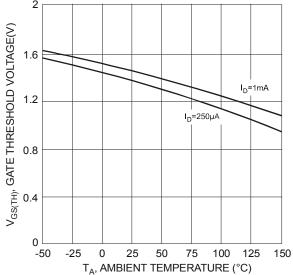
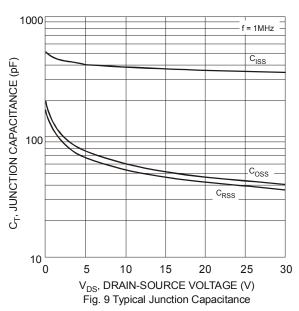
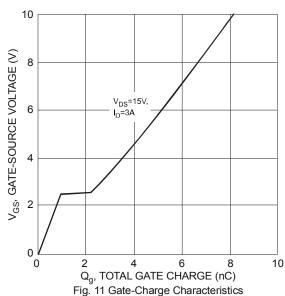
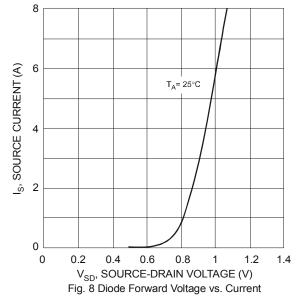


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







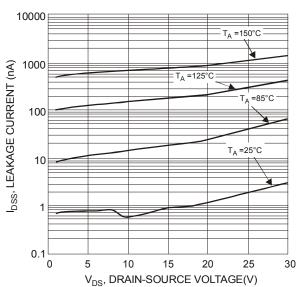
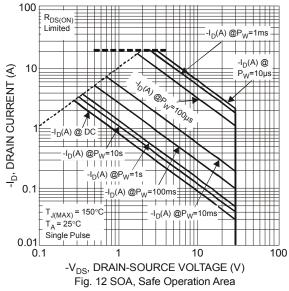
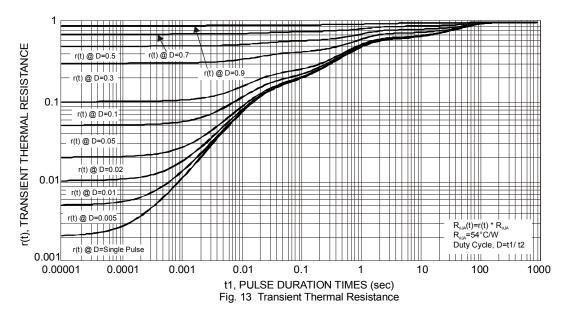


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage

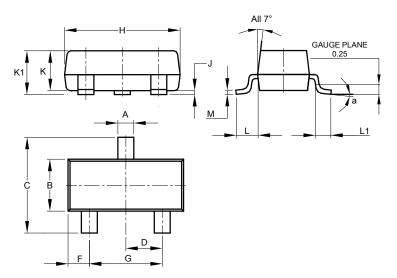






## **Package Outline Dimensions**

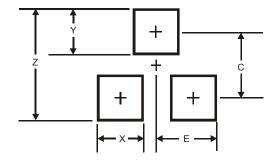
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23								
Dim	Min	Max	Тур					
Α	0.37	0.51	0.40					
В	1.20	1.40	1.30					
С	2.30	2.50	2.40					
D	0.89	1.03	0.915					
F	0.45	0.60	0.535					
G	1.78	2.05	1.83					
Н	2.80	3.00	2.90					
J	0.013	0.10	0.05					
K	0.890	1.00	0.975					
K1	0.903	1.10	1.025					
L	0.45	0.61	0.55					
L1	0.25	0.55	0.40					
M	<b>VI</b> 0.085 0.150 0.110							
α	α 8°							
All Dimensions in mm								

# Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Y	0.9
С	2.0
E	1.35



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